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Ching et al.(10) **Pub. No.: US 2023/0230935 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **SEMICONDUCTOR PACKAGE AND
METHOD OF MANUFACTURING THE SAME**(71) Applicant: **Taiwan Semiconductor
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ABSTRACT

A semiconductor package includes a substrate, a semiconductor die, a ring structure and a lid. The semiconductor die is disposed on the substrate. The ring structure is disposed on the substrate and surrounds the semiconductor die, where a first side of the semiconductor die is distant from an inner sidewall of the ring structure by a first gap, and a second side of the semiconductor die is distant from the inner sidewall of the ring structure by a second gap. The first side is opposite to the second side, and the first gap is less than the second gap. The lid is disposed on the ring structure and has a recess formed therein, and the recess overlaps with the first gap in a stacking direction of the ring structure and the lid.

